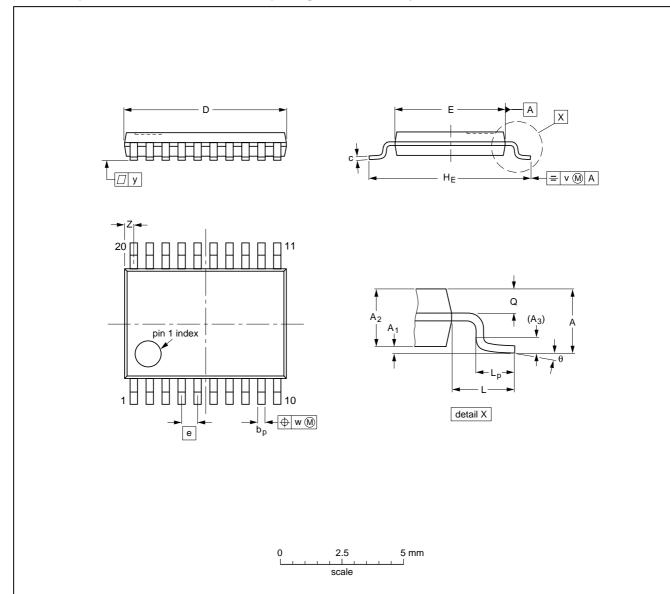
## **Philips Semiconductors**

# Package outline

## TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



### DIMENSIONS (mm are the original dimensions)

Dimensions (min are the original dimensions)																			
	UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(2)</sup>	e	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
	mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

### Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT360-1		MO-153				<del>99-12-27</del> 03-02-19	